Product/Process Change Notice - PCN 13_0192 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: AD5748/AD5750/AD5750-1/AD5750-2 Metal Edit and Reduced Package Type

Publication Date: 19-Feb-2014

Effectivity Date: 20-May-2014 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

The AD5748/AD5750/AD5750-1/AD5750-2 have undergone a minor metal mask edit. The package has been changed from 5mm x 5mm x 0.85mm LFCSP_VQ to 5mm x 5mm x 0.75mm LFCSP_WQ. There is no change in the solder land design.

Reason For Change

The metal edit improves electrical overstress (EOS) robustness.
The package change is to adhere to package process standardisation.

Impact of the change (positive or negative) on fit, form, function & reliability

The metal edit will result in an improvement in robustness with regards to power on EOS transients seen in some applications. The height of the package will be reduced from 0.85mm to 0.75mm. Chamfered edges on package will change to 90° edges. No impact to solder land design, function or reliability of parts

Product Identification *(this section will describe how to identify the changed material)*

Revised parts will be identified by the changed package (LFCSP_WQ) and date code 1421 onwards.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary.

Comments

The new package will be reflected in Rev F. of the AD5750/AD5750-1/AD5750-2 Datasheet and Rev B. of the AD5748 datasheet

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Supporting Documents

Attachment 1: Type: Package Outline Drawing

ADI_PCN_13_0192_Rev_-_CP_32_7.pdf

Attachment 2: Type: Qualification Plan Summary

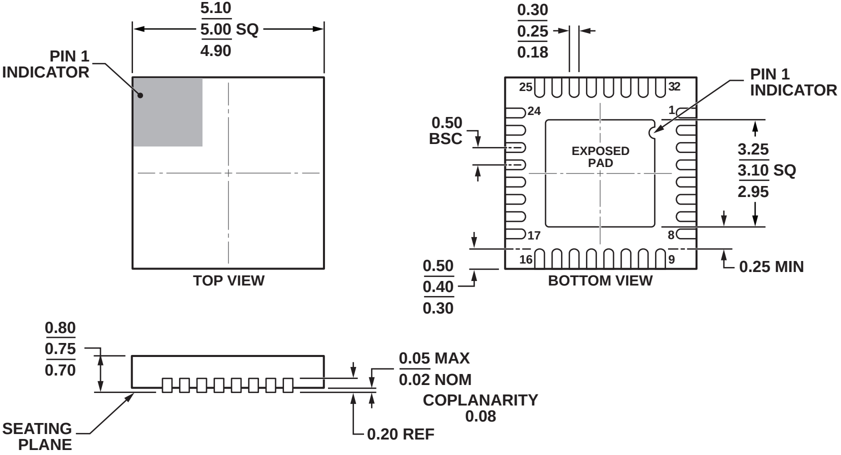
For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	**Europe:**	PCN_Europe@analog.com	**Japan:**	PCN_Japan@analog.com
				Rest of Asia:	PCN_ROA@analog.com

Appendix A - Affected ADI Models				
Added Parts On This Revision - Product Family / Model Number (14)				
AD5748 / AD5748ACPZ	AD5748 / AD5748ACPZ-RL7	AD5750 / AD5750ACPZ	AD5750 / AD5750ACPZ-REEL7	AD5750 / AD5750BCPZ
AD5750 / AD5750BCPZ-REEL7	AD5750-1 / AD5750-1ACPZ	AD5750-1 / AD5750-1ACPZ-REEL	AD5750-1 / AD5750-1ACPZ-REEL7	AD5750-1 / AD5750-1BCPZ
AD5750-1 / AD5750-1BCPZ-REEL	AD5750-1 / AD5750-1BCPZ-REEL7	AD5750-2 / AD5750-2BCPZ	AD5750-2 / AD5750-2BCPZ-RL7	

Appendix B - Revision History			
Rev	**Publish Date**	**Effectivity Date**	**Rev Description**
Rev. -	19-Feb-2014	20-May-2014	Initial Release

ANALOG DEVICES

32-Lead Lead Frame Chip Scale Package [LFCSP_WQ]
5 x 5 mm Body, Very Very Thin Quad
(CP-32-7)
Dimensions shown in millimeters



COMPLIANT TO JEDEC STANDARDS MO-220-WHHD.

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